

ABSTRACT OF THE INVENTION

An integrated heat dissipating device has a heat sink, a first set of fins, a second set of fins and at least one heat pipe. The heat sink has a thermal conductive block embedded therein and a through hole exposing the thermal conductive block from a top surface of the heat sink. The first set of fins has a plurality of horizontally extending fins stacked with each other along a vertical direction over the heat sink. The second set of fins is integrated by a plurality of vertically extending fins arranged in a curved shape between the heat sink and the first set of fins. The heat pipe has a vertical extension across the first set of fins and a horizontal extension underneath a bottom of the first set of fins. The horizontal extension is inserted into the through hole in contact with the thermal conductive block.